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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10008958	12/05/2001	257	620	2814	N. HA

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10008958	12/05/2001	257		2814	

**APPLICANTS: Sasaki Miki; Minami Toshifumi;

**CONTINUING DATA VERIFIED:
THIS APPLICATION IS A CON OF 09/135,740 08/18/1998

**FOREIGN APPLICATIONS VERIFIED:
JAPAN 9-234875 08/29/1997

PG-FUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no			
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no			
Verified and Acknowledged Examiners's initials			
TITLE : Semiconductor device and method for manufacturing the same incorporating a dicing technique for wafer separation and method for manufacturing the same			

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G
Assistant Examiner			
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.
			Print Fig.
Primary Examiner		Application Examiner	
PREPARED FOR ISSUE			
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